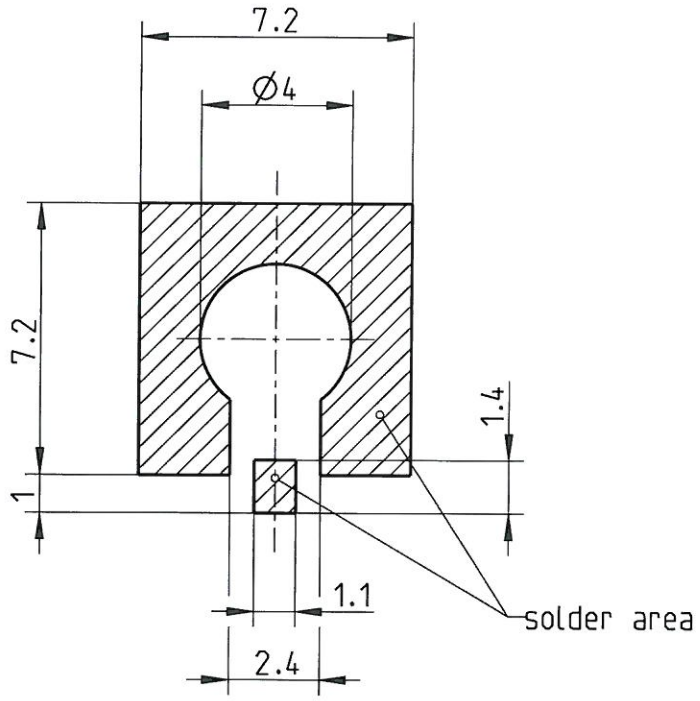
Leiterplatten-Layout
PCB layout
B 120 b



A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.
Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.
In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Formblatt: TCC_FB_05_PE_A4_Einzelteil
Pfad: i:\Proe-Config\Rahmen\
Datei: A4_LANDSCAPE_EDB.FRM
Version: 1.2

Dimensions in mm

ISO-Projektion Methode E

a00	10-s255	M_Wallner	14.04.2010
200	10-v078	J_Peterander	11.02.2010
100	10-m012	T_Stadler	11.01.2010
rev.	change-no	name	date

Rosenberger
Hochfrequenztechnik
84526 Tittmoning
Pro/ENGINEER

general tolerance
ISO 2768 m-H
RN 006-01 dimensions <0,5 and symmetry

	date	name
drawn	11.01.2010	T_Stadler
check.	16.04.10	
appr.	16.04.10	
dimensioning incl. finish		

distribution to:

FE	AZ	QSM	RMT	.
X	.	.	.	.

scale: 5:1
weight[g]:
surface[mm²]:
material:

title:
Leiterplatten-Layout
PCB layout

drawing-no..: MB_120B
sheet: 1
of: 1

remarks: .